

SVCP 標準垂直連續電鍍銅設備

STANDARD VERTICAL CONTINUOUS COPPER PLATING EQUIPMENT



新型第M288080號

特色 / FEATURES

- 標準化設計降低設備購置成本，縮短出貨時間
- 可依不同的製程需求，選擇不同的設備配置
- 可搭配自動或手動上板及下板
- 適用於印刷電路板，一次銅電鍍製程
- 板件厚度由0.134~4.0 mm 不須框架及治具輔助生產
- 品質一致的鍍層厚度均勻性
- 高縱橫比之通孔、盲孔及填盲孔、填通孔分佈力有傑出的表現
- 線內自動藥水剝掛
- 容易操作及維護
- 產品應用：
 - A 規：自動上/下料，搭配不溶性陽極
全板電鍍；MB 板、汽車板、HDI通/盲/填孔電鍍
 - B 規：自動上/下料，搭配可溶性陽極
全板電鍍；MB 板、汽車板、HDI通/盲孔電鍍
 - C 規：手動上/下料，搭配可溶性陽極
軟板通/盲孔電鍍，加框輔助生產
- Standardization design, lower cost and shorten delivery time.
- Select different configuration according to different processes.
- Match with automation and manual loading/unloading.
- Apply to panel plating.
- No auxiliary frame and jig to be used for board thickness 0.134~4.0 mm during production.
- Uniform distribution of plating quality.
- Remarkable throwing power of high aspect ratio for through hole, blind via, via filling and through hole filling plating.
- Auto online chemical stripping.
- Easy operation and maintenance.
- Application:
 - Class A: Auto load/unload with insoluble anode
Panel plating for MB board, motor board, HDI through/blind/via filling.
 - Class B: Auto load/unload with soluble anode
Panel plating for MB board, motor board, HDI through/blind via plating.
 - Class C: Manual load/unload with soluble anode
Flexible Panel through/blind via plating with frame.

規格 / SPECIFICATION

- 板片尺寸：24" x 24" (max.); 16" x 14" (min.)
- 板片厚度：0.1 mm + Copper foil H/H ~ 4.0 mm
- 線速度：0.3~1.5m/min (可調)
- 電鍍視窗：610x 5280L (mm)/Chamber
- 銅缸數：1~6 (選擇)
- 電流密度：30 ASF (max.)可溶性磷銅球陽極
40 ASF (max.) 不可溶性陽極
- 陽極型式：鈦籃式可溶性磷銅球或不溶性陽極
(Ti mesh with IrO₂ coating)
- 陰極型式：垂直單邊夾持方式
- Panel size : 24" x 24" (max.); 16" x 14" (min.)
- Board thickness : 0.1 mm + Copper foil H/H ~ 4.0 mm
- Line speed : 0.3 ~ 1.5m/min (Adjustable)
- Plating window : 610x 5280L (mm)/Chamber
- Plating cell : 1~6 Chamber (Option)
- Current density : 30 ASF (max.) for Soluble anode
40 ASF (max.) for Insoluble anode
- Anode : Soluble copper ball in Ti basket or Insoluble anode
(Ti mesh with IrO₂ coating)
- Cathode : Vertical clamping system

總公司 Headquarter

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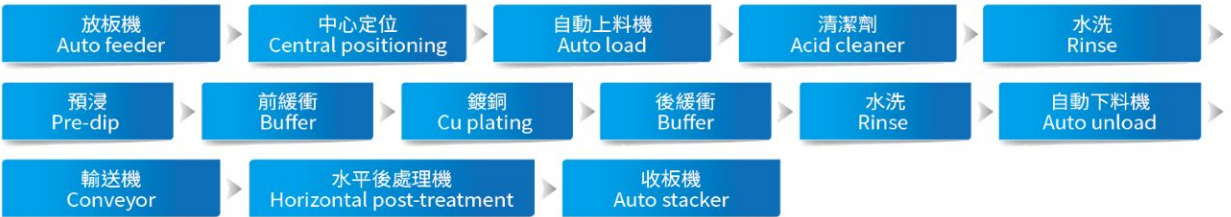
SVCP(DT) 標準垂直連續電鍍銅設備(雙列型)

STANDARD VERTICAL CONTINUOUS COPPER PLATING EQUIPMENT(DOUBLE TYPE)



新型第M288080號

流程 / PROCESS



PERFORMANCE: COPPER THICKNESS DISTRIBUTION

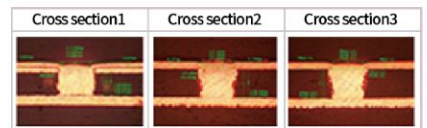
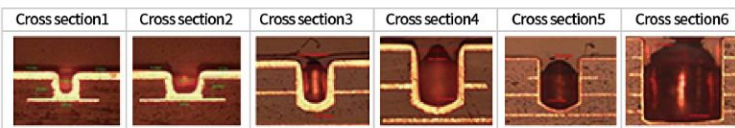
Within 15 mm boundary	Plating thickness (mil)	Depth size of panel (inch)	Standard deviation σ (mil)	Distribution $3\sigma / X_{mean} \times 100\%$	Range Th. (Max.-Min.) (mil)
	1	18~24	0.025 ~ 0.04	$\leq 10\%$	0.15 ~ 0.25

THROWING POWER OF BLIND VIA (DC):

	Cross section1	Cross section2	Cross section3	Cross section4	Cross section5	Cross section6
Hole diameter (mil)	4	5.6	7.8	11.8	23.5	47
C.D. (ASD)	3.2	3.2	1.2	1.2	1.2	12
Board thickness (mil)	2.6	2.6	9.5	13.3	28.3	47
A/R	0.65	0.46	1.22	1.13	1.20	1
TP	90%	94%	85%	85%	82%	80%
KneeTP	93%	95%	88%	87%	85%	82%

VIA FILLING (DC):

	Cross section1	Cross section2	Cross section3
Hole diameter (mil)	5.3		
C.D. (ASD)	2.2		
Board thickness (mil)	4		
A/R	0.75		
Dimple	5.1	5.7	5.4



THROWING POWER OF THROUGH HOLE (DC/PPR):

	Cross section1	Cross section2	Cross section1	Cross section2	Cross section3
Hole diameter (mil)	8		11.8		
C.D. (ASD)	1.6		1.8		
Board thickness (mil)	3.5		62	93	
A/R	0.4		5.3	8	
TP	140%	138%	90%	94%	85%
KneeTP	123%	120%	93%	95%	88%

